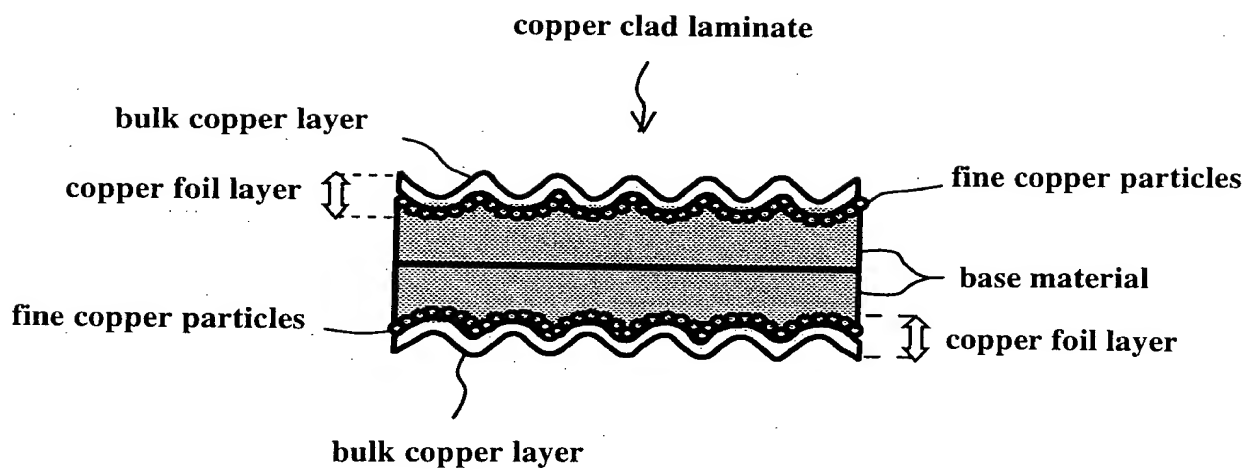
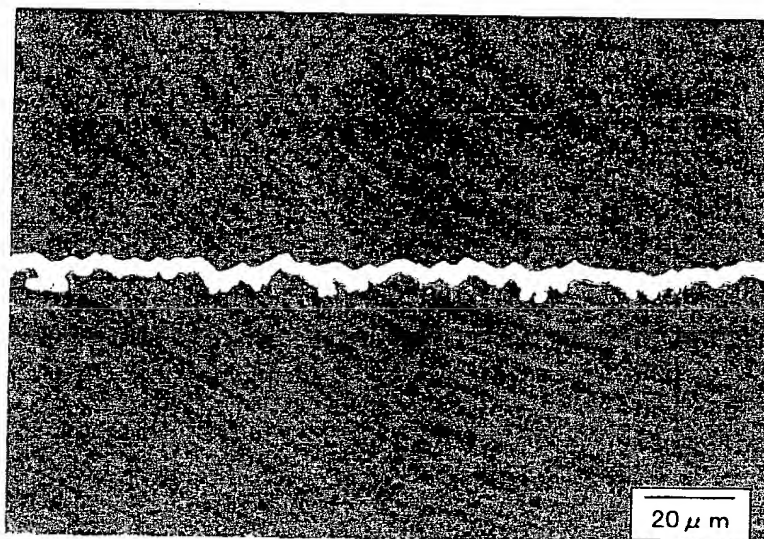


FIG. 1



09855382 051501

FIG. 2



0935330 051601
T05T50 28E5850

FIG. 3

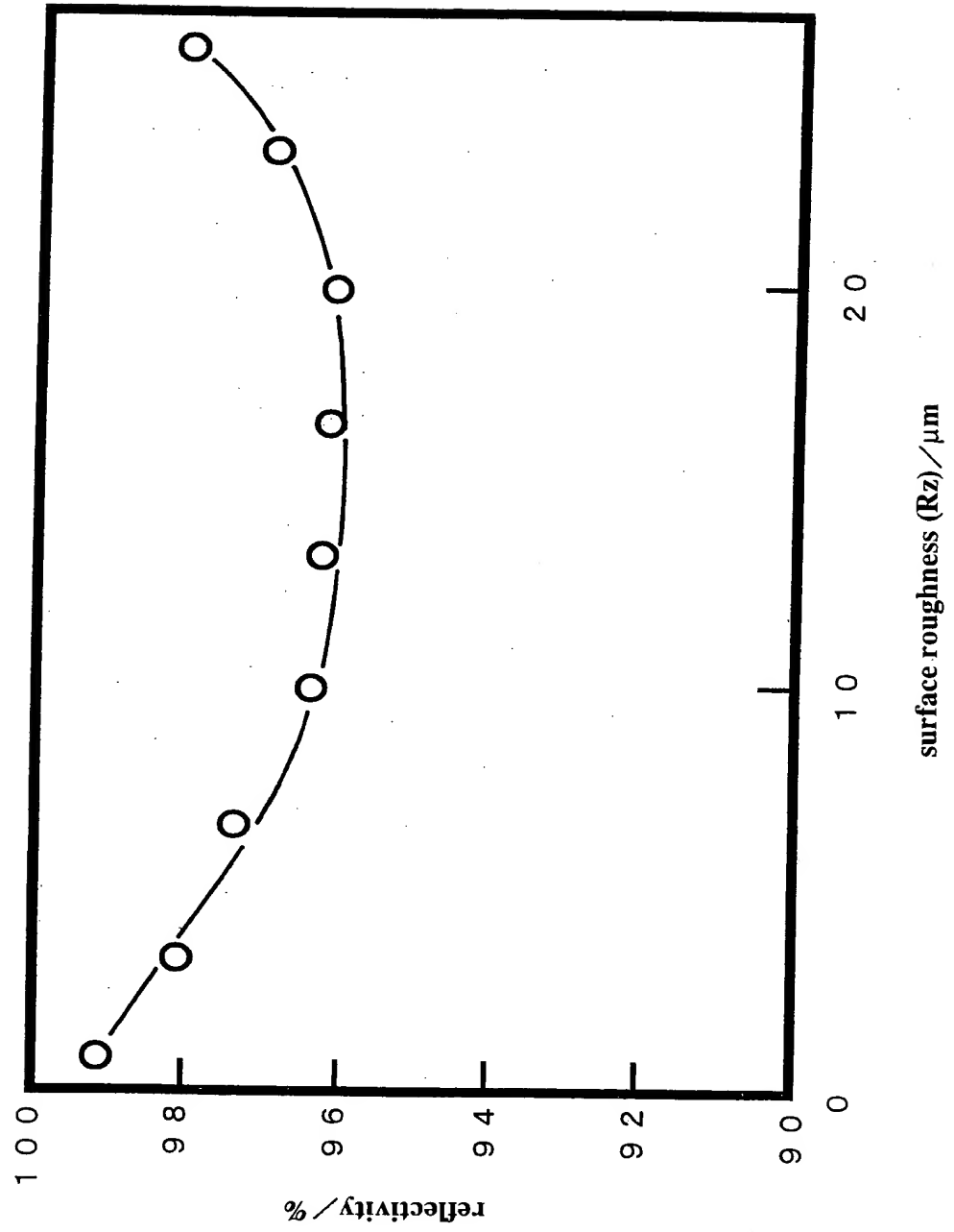
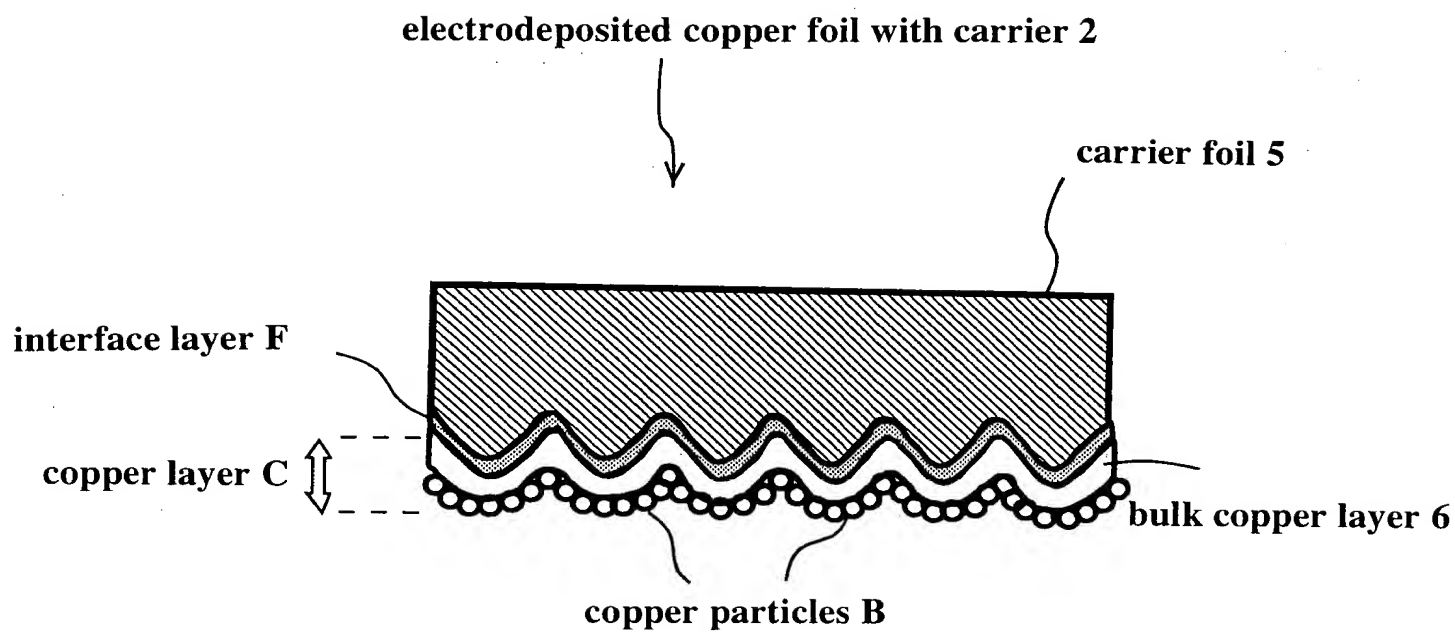


FIG. 4



09055382-051501
FOI 2855860

FIG. 5

(a) Manufacturing of copper clad laminate

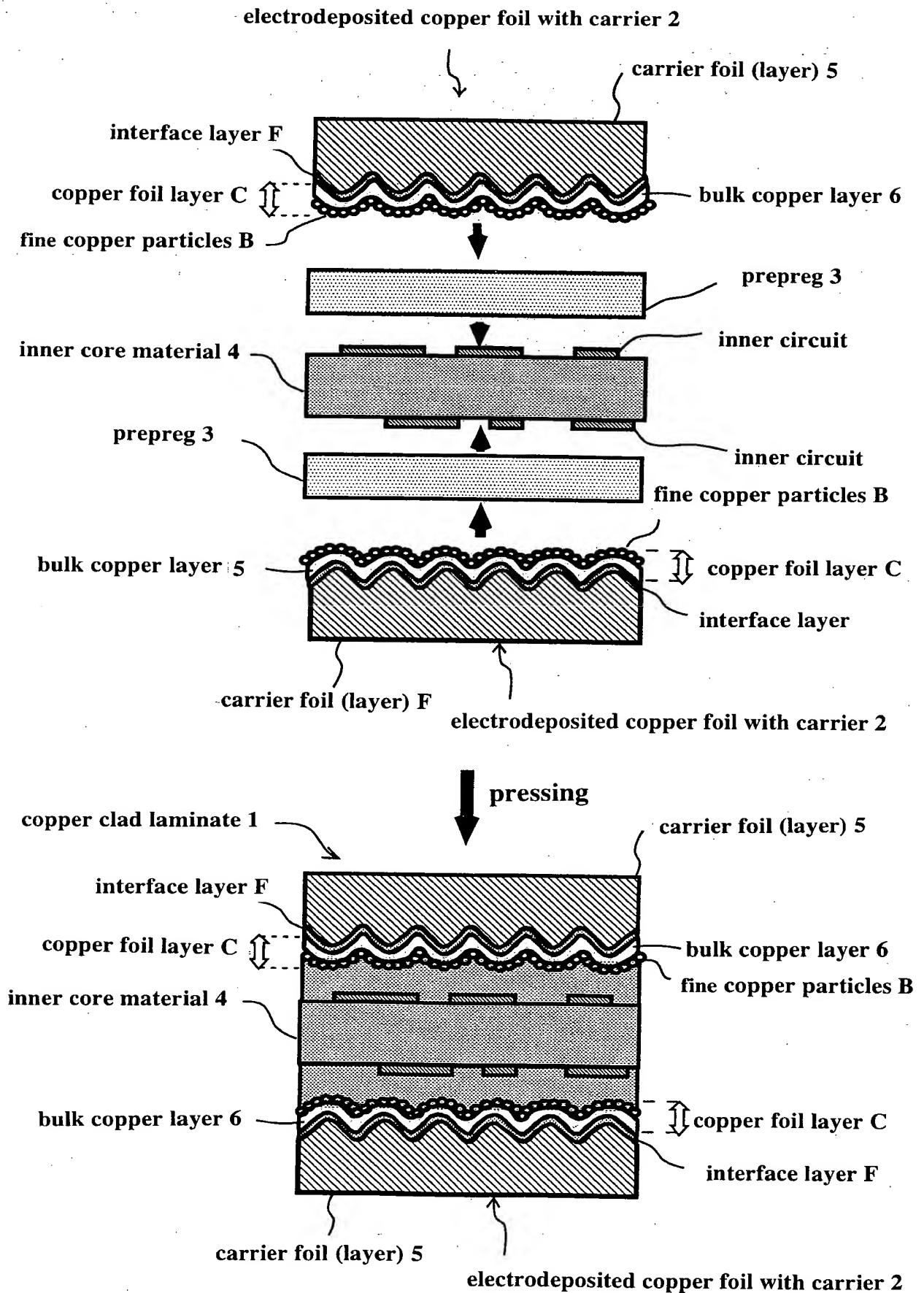
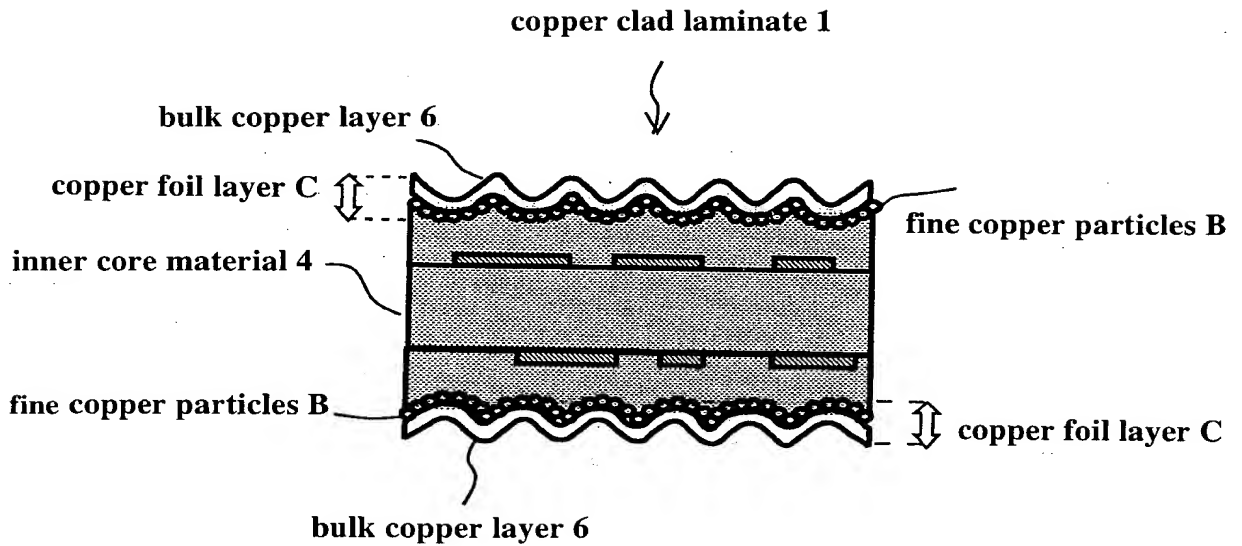


FIG. 6

(b) Peeling of Carrier Foil



(c) Laser Treatment for Forming Holes

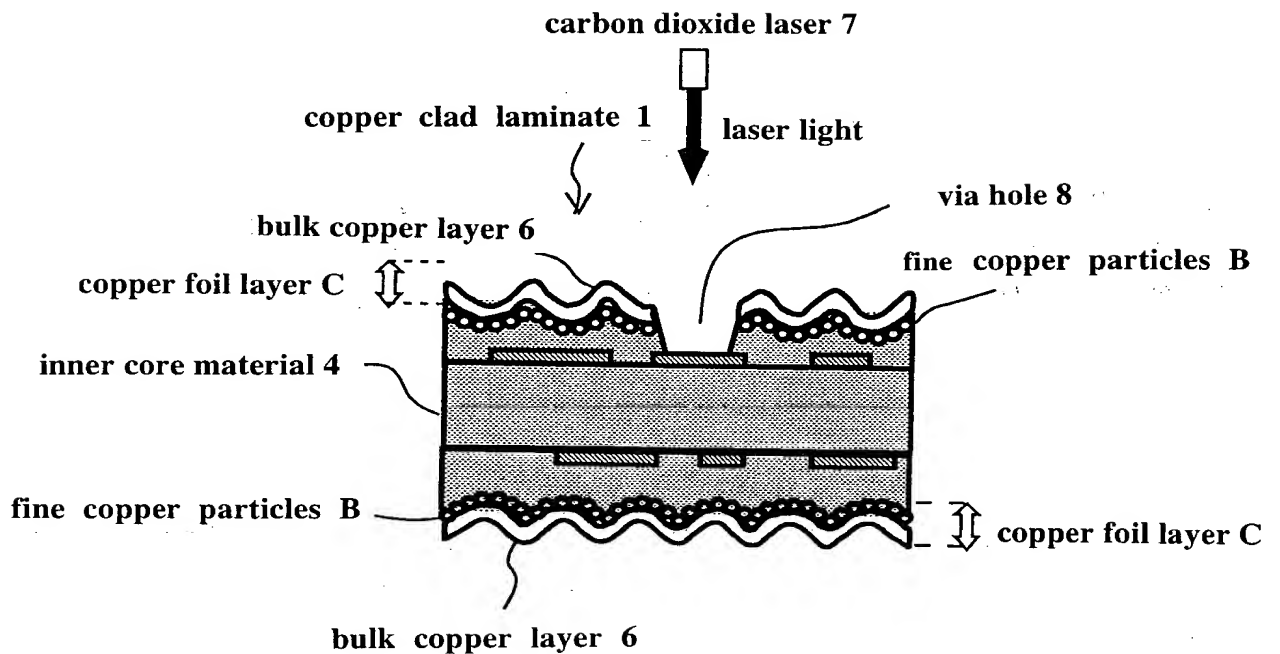
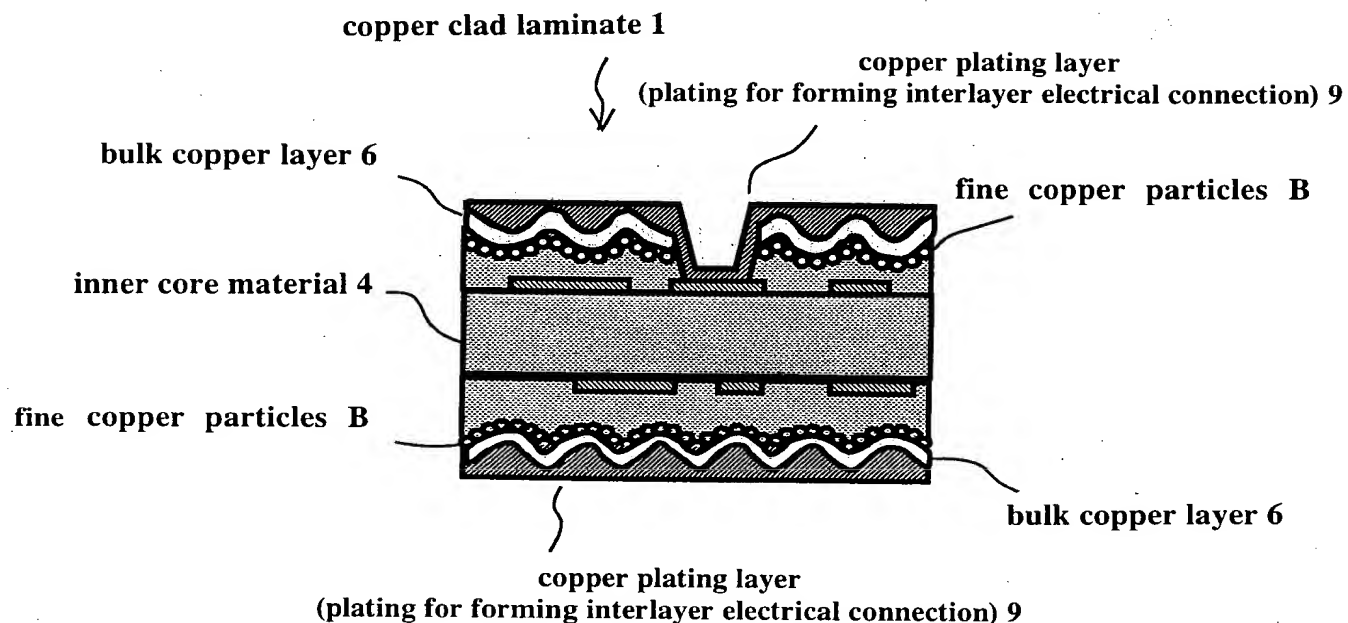


FIG. 7

(d) Copper Plating for Forming Interlayer Electrical Connection



(e) Forming Etching Resist Layers

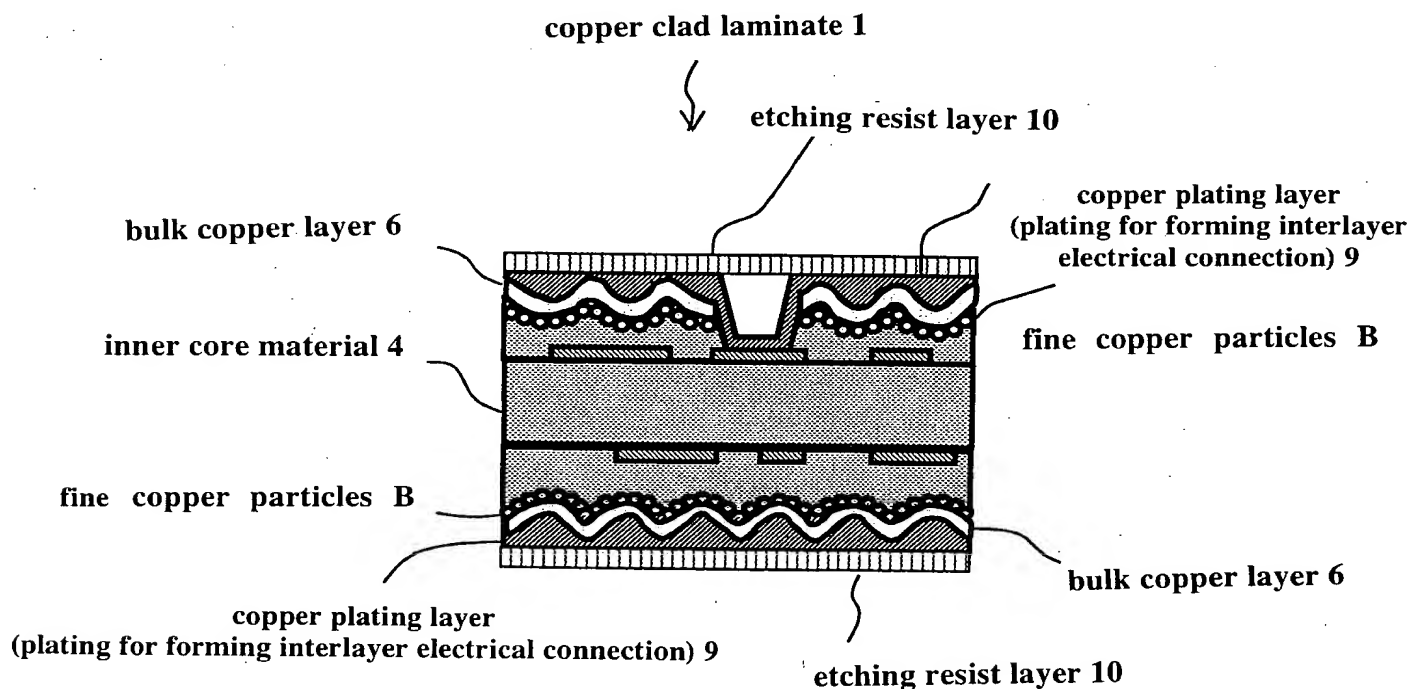
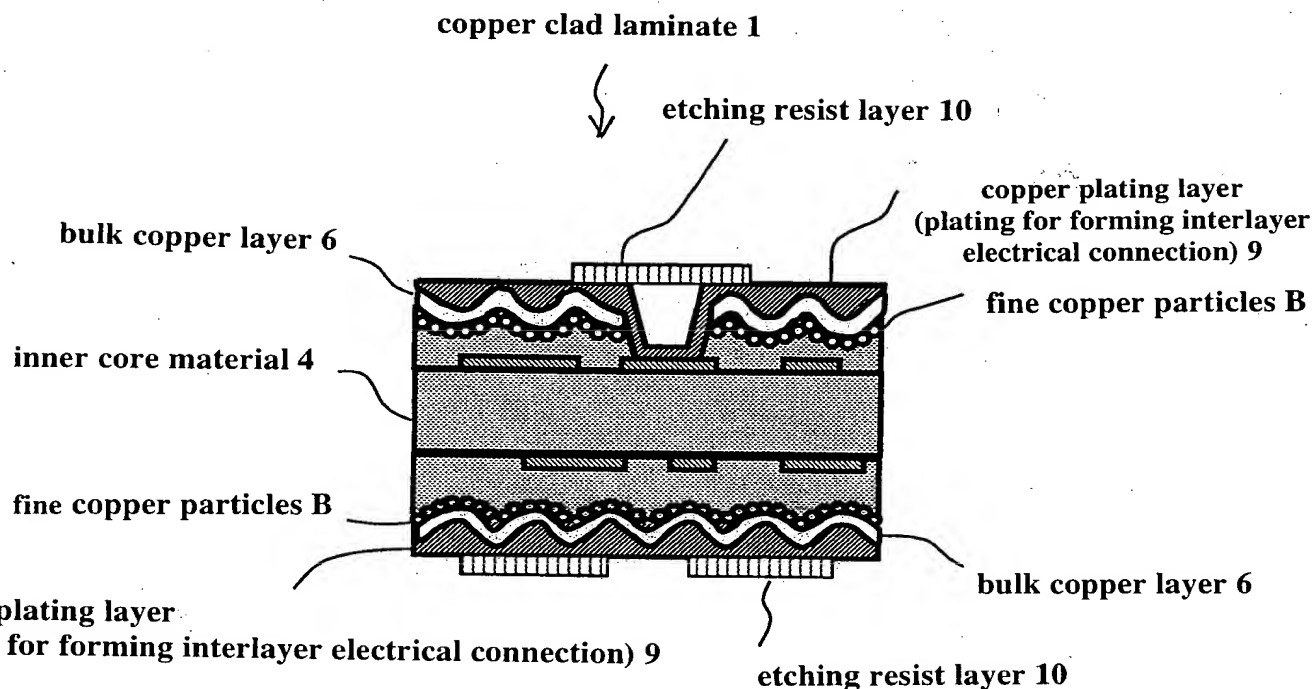


FIG. 8

(f) Exposing and Developing the Etching Resist Layers



(g) Copper Etching

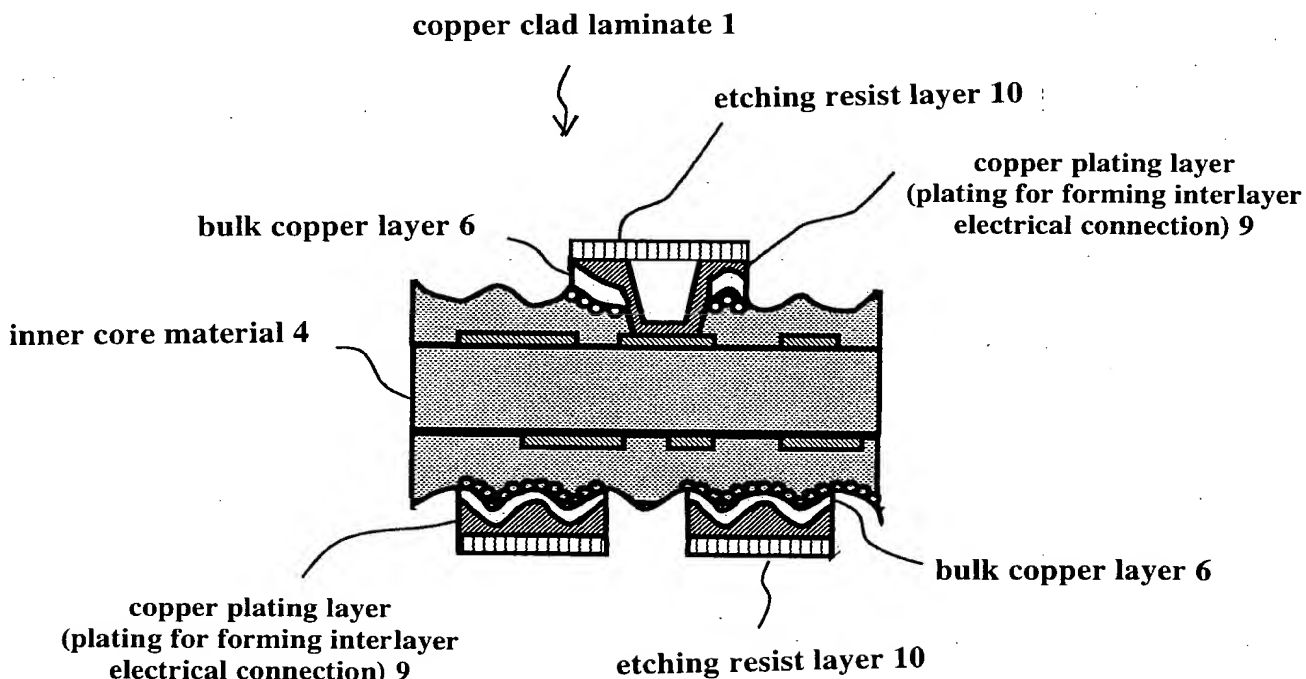
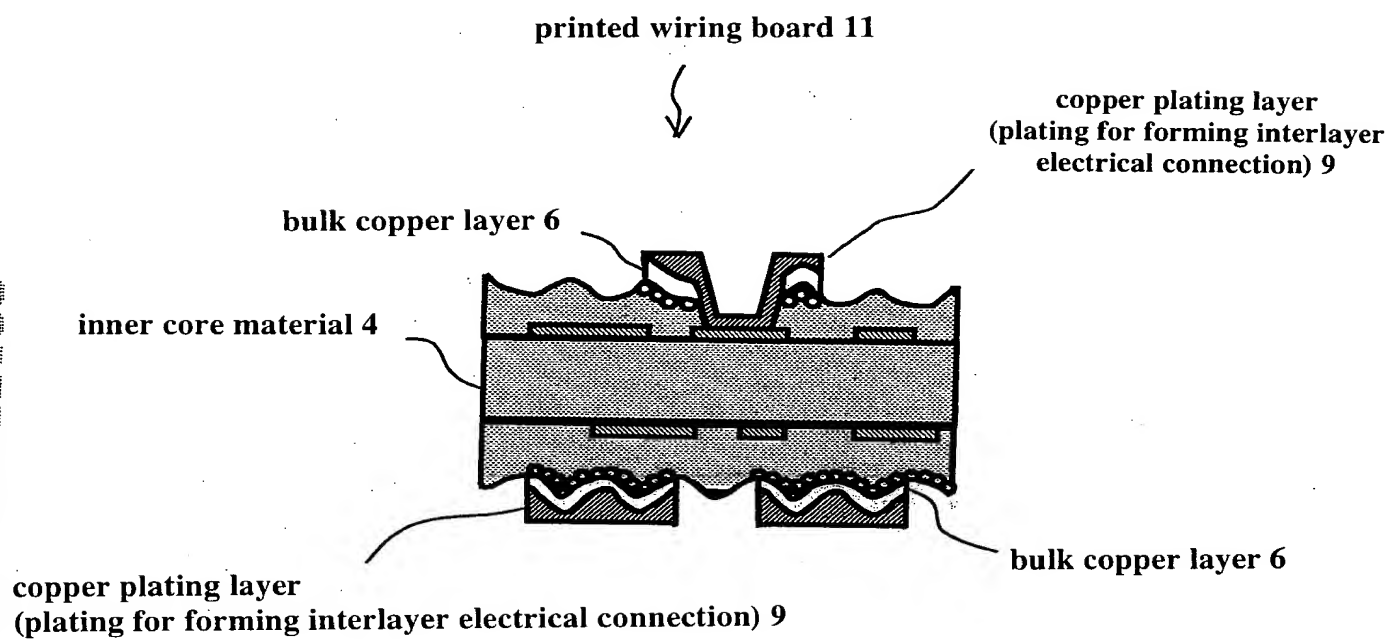


FIG. 9

(h) Peering of Etching Resist Layers



09255382-051501
T05150-28255382